

(0.635 mm) .025"

MIT SERIES

# MIXED TECHNOLOGY HEADER

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MIT](http://www.samtec.com?MIT)

**Insulator Material:**

Liquid Crystal Polymer

**Contact Material:**

Phosphor Bronze

**Plating:**

Au or Sn over

50 μ" (1.27 μm) Ni

**Operating Temp Range:**

-55 °C to +125 °C

**Voltage Rating:**

275 VAC

**Max Cycles:**

100

**RoHS Compliant:**

Yes

**Board Mates:**  
MIS

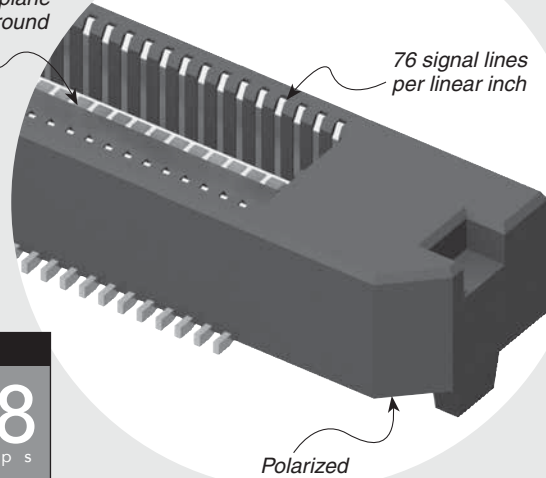
**Standoffs:**  
SO



Integral metal plane for power or ground

76 signal lines per linear inch

Choice of mated heights



Polarized

## HIGH-SPEED CHANNEL PERFORMANCE

MIT/MIS @ 5 mm Mated Stack Height  
Rating based on Samtec reference channel.  
For full SI performance data visit [Samtec.com](http://Samtec.com)  
or contact [SIG@samtec.com](mailto:SIG@samtec.com)

**28**  
Gbps

## PROCESSING

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0.10 mm) .004" max (019-057)

**Board Stacking:**

For applications requiring more than two connectors per board contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## ALSO AVAILABLE (MOQ Required)

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ" (0.76 μm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row



**-019, -038, -057**  
(38 total positions per bank)

Specify LEAD STYLE from chart

**-F**  
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

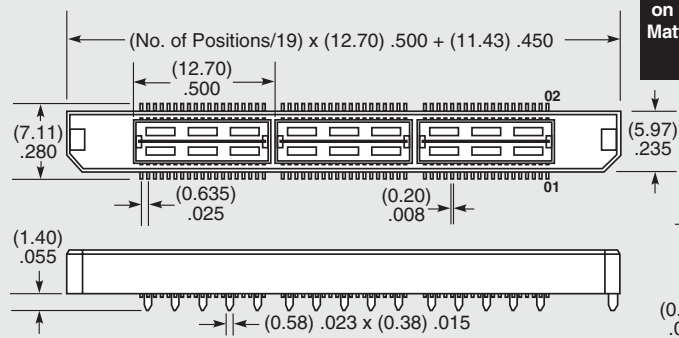
**-L**  
= 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

**-C\***  
= Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, 10 μ" (0.25 μm) min Au over 50 μ" (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails

**-K**  
= (7.00 mm) .275" DIA Polyimide film Pick & Place Pad

**-TR**  
= Tape & Reel

LEAD STYLE	A
-01	(4.27) .168
-02	(7.26) .286



\*Note:  
-C Plating passes 10 year MFG testing

MIS LEAD STYLE	MATED HEIGHT*	
	MIT LEAD STYLE -01	-02
-01	(5.00) .197	(8.00) .315

\*Processing conditions will affect mated height. See SO Series for board space tolerances.

**Note:**  
Some lengths, styles and options are non-standard, non-returnable.

**Note:** Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.